

N-channel Enhanced mode TO-220F MOSFET

Features

- High ruggedness
- Low R_{DS(ON)} (Typ 0.57Ω)@V_{GS}=10V
 Low Gate Charge (Typ 57nC)
- Improved dv/dt Capability
- 100% Avalanche Tested
- Application: LED , Charge, PC Power

General Description

This power MOSFET is produced with advanced technology of SAMWIN. This technology enable the power MOSFET to have better characteristics, including fast switching time, low on resistance, low gate charge and especially excellent avalanche characteristics.

BV_{DSS} : 650V

R_{DS(ON)} : 0.57Ω

:15A

Order Codes

Item	Sales Type	Marking	Package	Packaging
1	SW F 15N65D	SW15N65D	TO-220F	TUBE

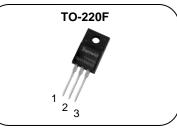
Absolute maximum ratings

Symbol	Parameter		Value	Unit
V _{DSS}	Drain to source voltage		650	V
	Continuous drain current (@T _c =25°C)		15*	А
Ι _D	Continuous drain current (@T _C =100°C)		9.5*	A
I _{DM}	Drain current pulsed	(note 1)	60	A
V _{GS}	Gate to source voltage		±30	V
E _{AS}	Single pulsed avalanche energy	(note 2)	263	mJ
E _{AR}	Repetitive avalanche energy	(note 1)	25	mJ
dv/dt	Peak diode recovery dv/dt	(note 3)	5	V/ns
	Total power dissipation (@T _C =25°C)		33	W
P _D	Derating factor above 25°C		0.26	W/ºC
T_{STG},T_{J}	Operating junction temperature & storage te	emperature	-55 ~ + 150	°C
TL	Maximum lead temperature for soldering purpose, 1/8 from case for 5 seconds.		300	°C

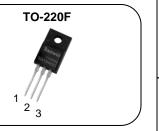
*. Drain current is limited by junction temperature.

Thermal characteristics

Symbol	Parameter	Value	Unit
R _{thjc}	Thermal resistance, Junction to case	3.8	°C/W
R _{thja}	Thermal resistance, Junction to ambient	49	°C/W



1. Gate 2. Drain 3. Source





Electrical characteristic ($T_{\rm C}$ = 25°C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Off charac	teristics			1	1	1
BV _{DSS}	Drain to source breakdown voltage	V _{GS} =0V, I _D =250uA	650			V
ΔΒV _{DSS} / ΔΤ _J	Breakdown voltage temperature coefficient	I _D =250uA, referenced to 25°C		0.68		V/ºC
I _{DSS}	Drain to source leakage current	V _{DS} =650V, V _{GS} =0V			1	uA
		V _{DS} =520V, T _C =125°C			50	uA
I	Gate to source leakage current, forward	V _{GS} =30V, V _{DS} =0V	R	5	100	nA
I _{GSS}	Gate to source leakage current, reverse	V _{GS} =-30V, V _{DS} =0V	6		-100	nA
On charact	teristics					
V _{GS(TH)}	Gate threshold voltage	$V_{DS}=V_{GS}$, $I_{D}=250$ uA	2.5		4.5	V
R _{DS(ON)}	Drain to source on state resistance	V _{GS} =10V, I _D =7.5A		0.57	0.72	Ω
G _{fs}	Forward transconductance	V _{DS} =30V, I _D =7.5A	×	13		S
Dynamic c	haracteristics					4
C _{iss}	Input capacitance		A	2646		pF
C _{oss}	Output capacitance	V _{GS} =0V, V _{DS} =25V, f=1MHz		195		
C _{rss}	Reverse transfer capacitance		2	18		
t _{d(on)}	Turn on delay time			35		
t _r	Rising time	V_{DS} =325V, I_{D} =15A, R_{G} =25 Ω ,		58		- ns
t _{d(off)}	Turn off delay time	V _{GS} =10V (note 4,5)		117		
t _f	Fall time			50		
Q _g	Total gate charge	V _{DS} =520V, V _{GS} =10V, I _D =15A,		57		nC
Q _{gs}	Gate-source charge	Ig=4mA		15		
Q _{gd}	Gate-drain charge	(note 4,5)		23		
R _g	Gate resistance	V _{DS} =0V, Scan F mode		1.0		Ω

Source to drain diode ratings characteristics

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _S	Continuous source current	Integral reverse p-n Junction diode in the MOSFET			15	А
I _{SM}	Pulsed source current				60	А
V _{SD}	Diode forward voltage drop.	I _S =15A, V _{GS} =0V			1.4	V
t _{rr}	Reverse recovery time	I _S =15A, V _{GS} =0V, dI _F /dt=100A/us		499		ns
Q _{rr}	Reverse recovery charge			6.3		uC

※. Notes

Repeatitive rating : pulse width limited by junction temperature. 1.

L =2.33mH, IAS =15A, VDD=50V, RG=25 Ω , Starting TJ = 25°C I_{SD} ≤ 15A, di/dt = 100A/us, V_{DD} ≤ BV_{DSS}, Staring T_J =25°C Pulse Test : Pulse Width ≤ 300us, duty cycle ≤ 2%. 2.

3.

4.

5. Essentially independent of operating temperature.



Fig. 1. On-state characteristics

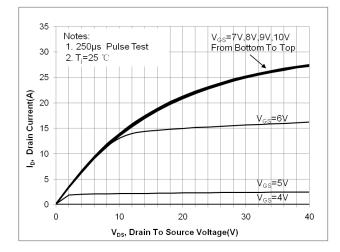
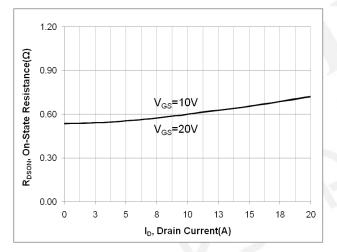
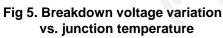


Fig. 3. On-resistance variation vs. drain current and gate voltage





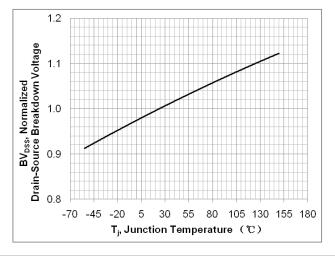
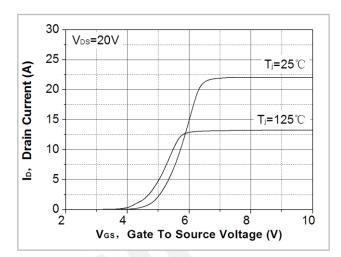
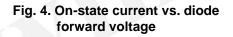


Fig. 2. Transfer Characteristics





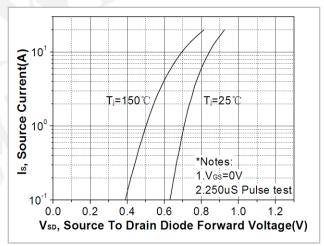
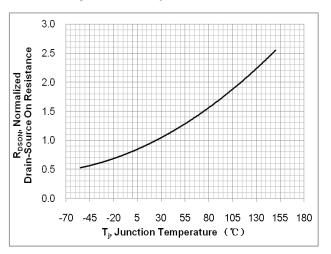


Fig. 6. On-resistance variation vs. junction temperature



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Fig. 7. Gate charge characteristics

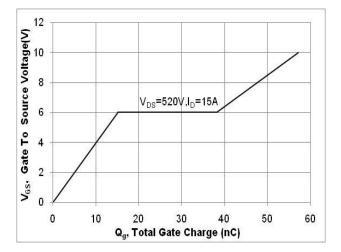


Fig. 9. Maximum safe operating area

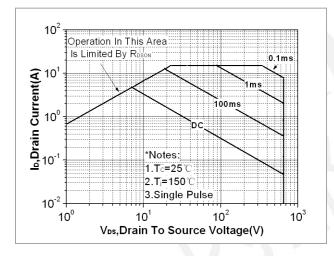




Fig. 10. Transient thermal response curve

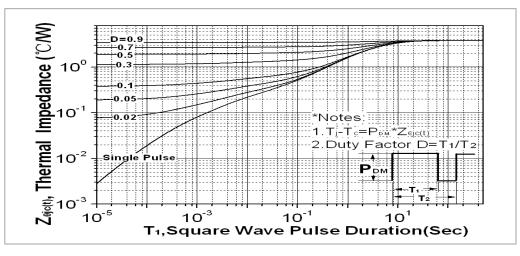
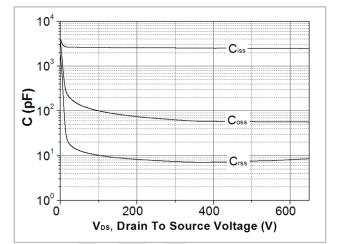


Fig. 8. Capacitance Characteristics



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Fig. 11. Gate charge test circuit & waveform

Same type as DUT

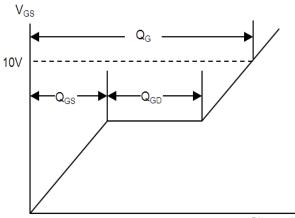
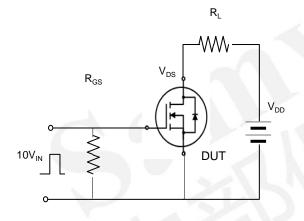
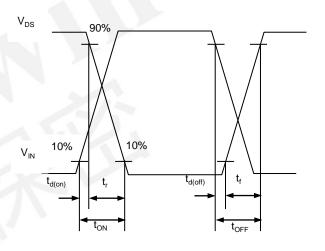


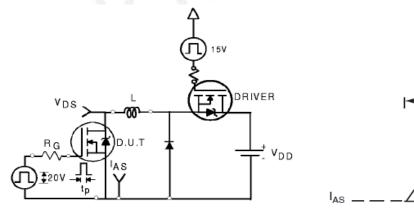


Fig. 12. Switching time test circuit & waveform









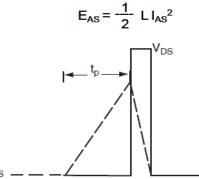
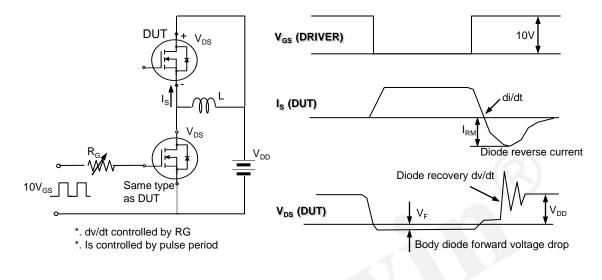


Fig. 14. Peak diode recovery dv/dt test circuit & waveform



DISCLAIMER

* All the data & curve in this document was tested in XI' AN SEMIPOWER TESTING & APPLICATION CENTE R.

* This product has passed the PCT,TC,HTRB,HTGB,HAST,PC and Solderdunk reliability testing

- * Qualification standards can also be found on the Web site (http://www.semipower.com.
- * Suggestions for improvement are appreciated, Please send your suggestions to samwin@samwinsemi.com

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